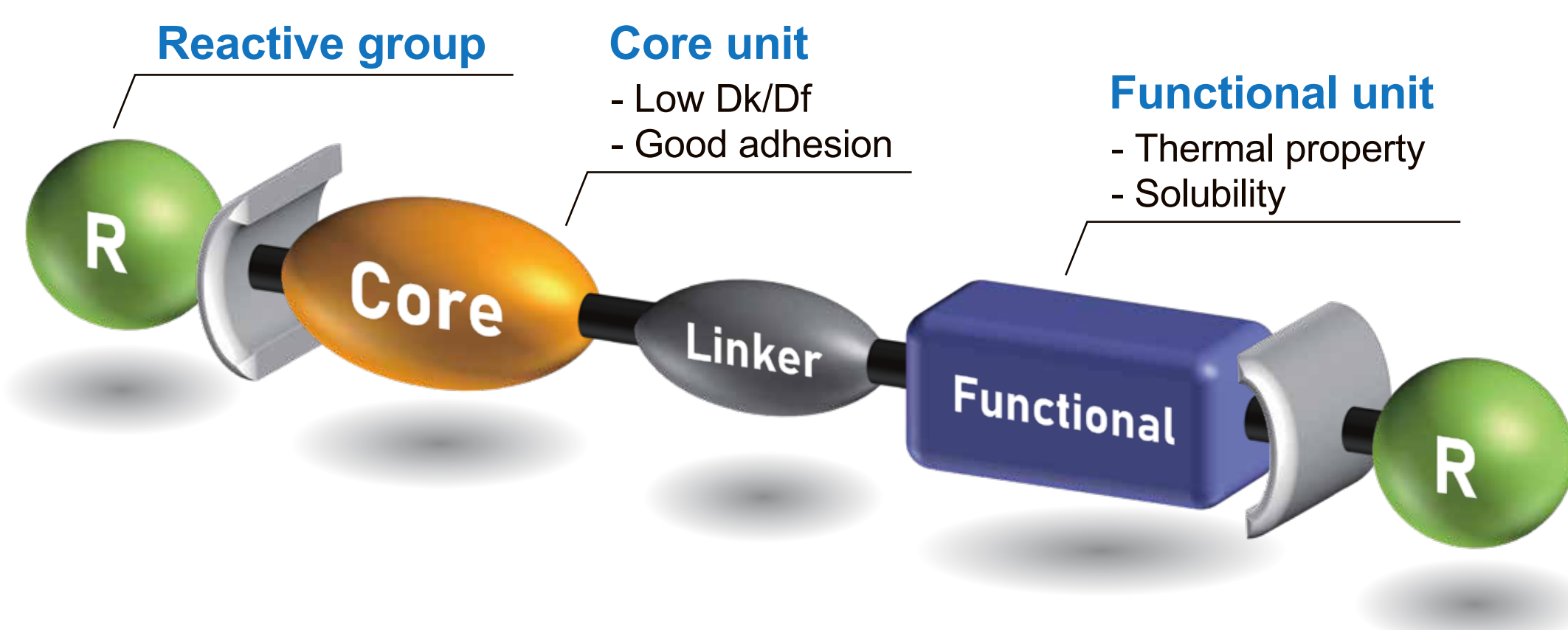
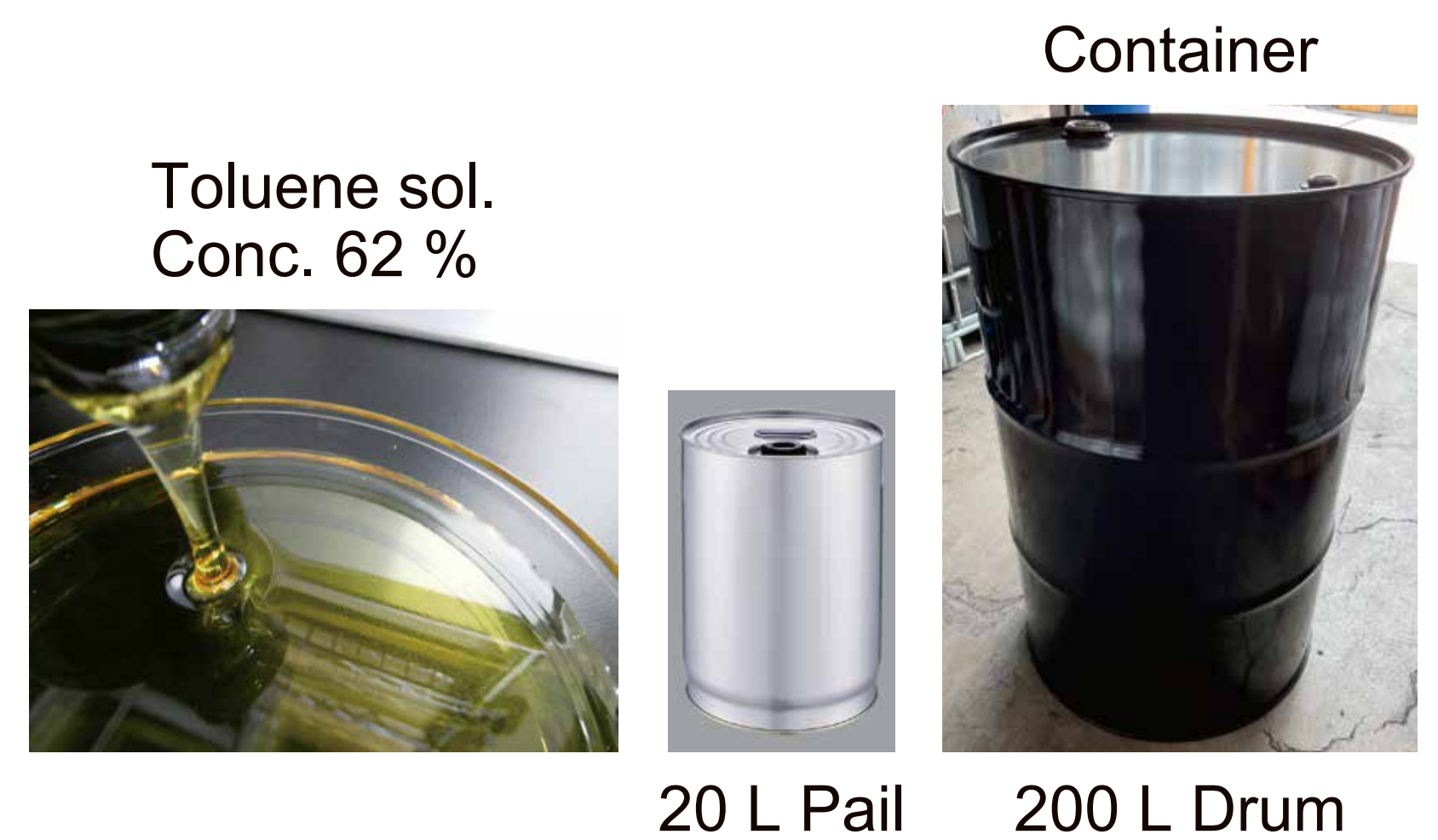


CG series Low Dk/Df Thermosetting Polymer

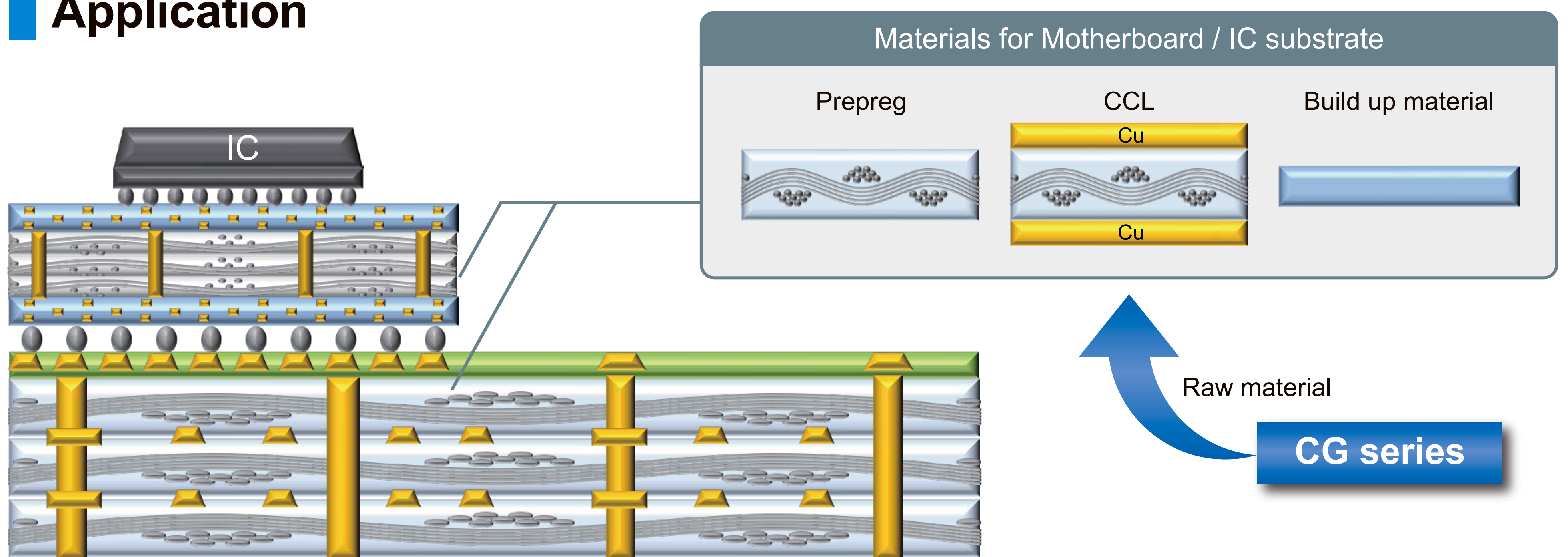
Design Concept



Product form



Application



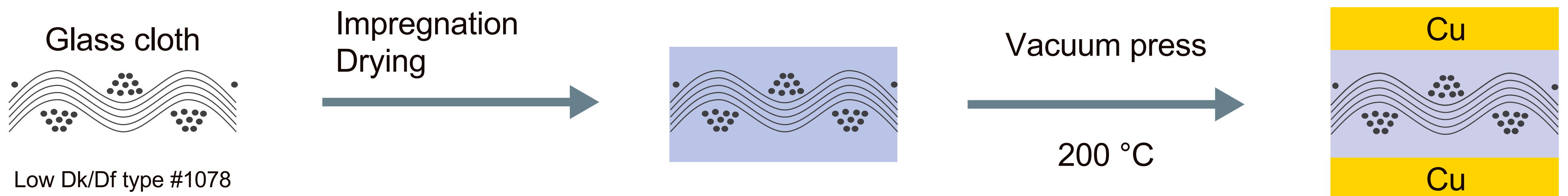
Properties of cured film

	CG-7001	CG-7003
Feature	Low Df High Tg	Low Df Good adhesion
Core + Functional	Type I	Type III
R	Radical-curable	
Dk (10 GHz)	2.6	2.6
Df (10 GHz)	0.0009	0.0011
Tg (°C, DMA)	233	172
T _d ⁵ (°C)	399	390
Peel strength (N/mm)	0.6	0.8
Appearance		

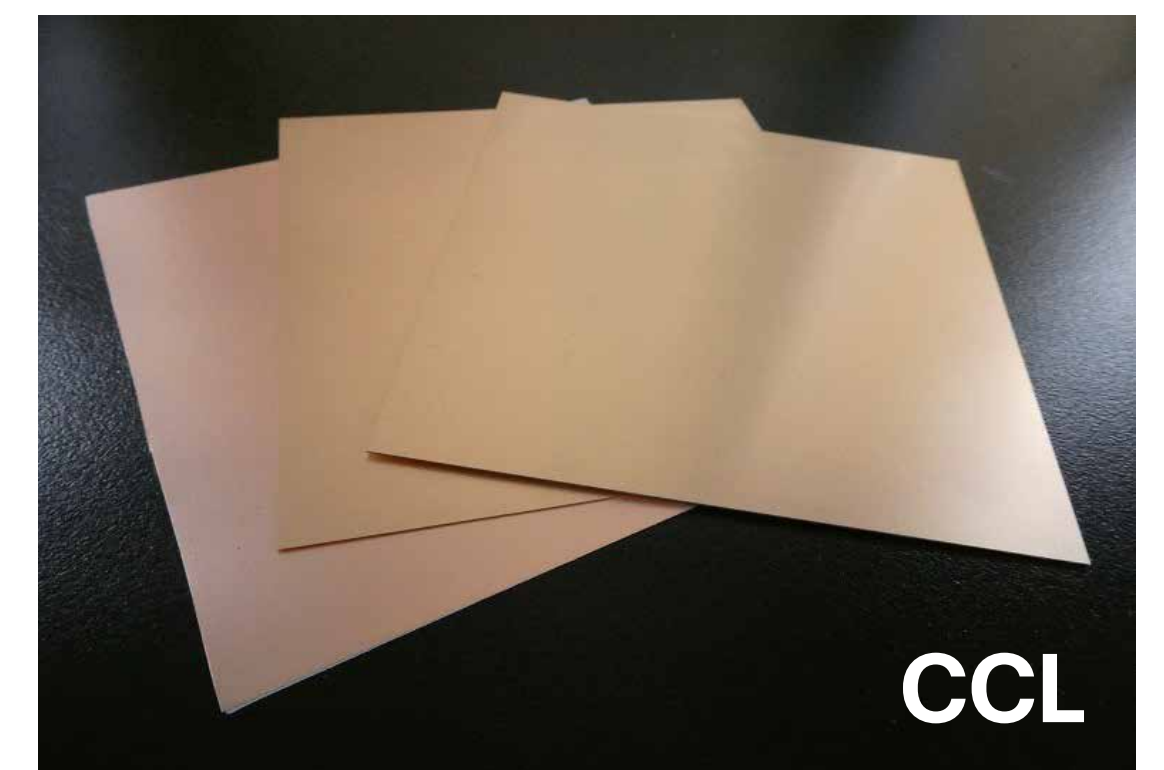
Composition: CG polymer / Organic peroxide. Cured at 200 °C

CG series Low Dk/Df Thermosetting Polymer

Evaluation examples as CCL



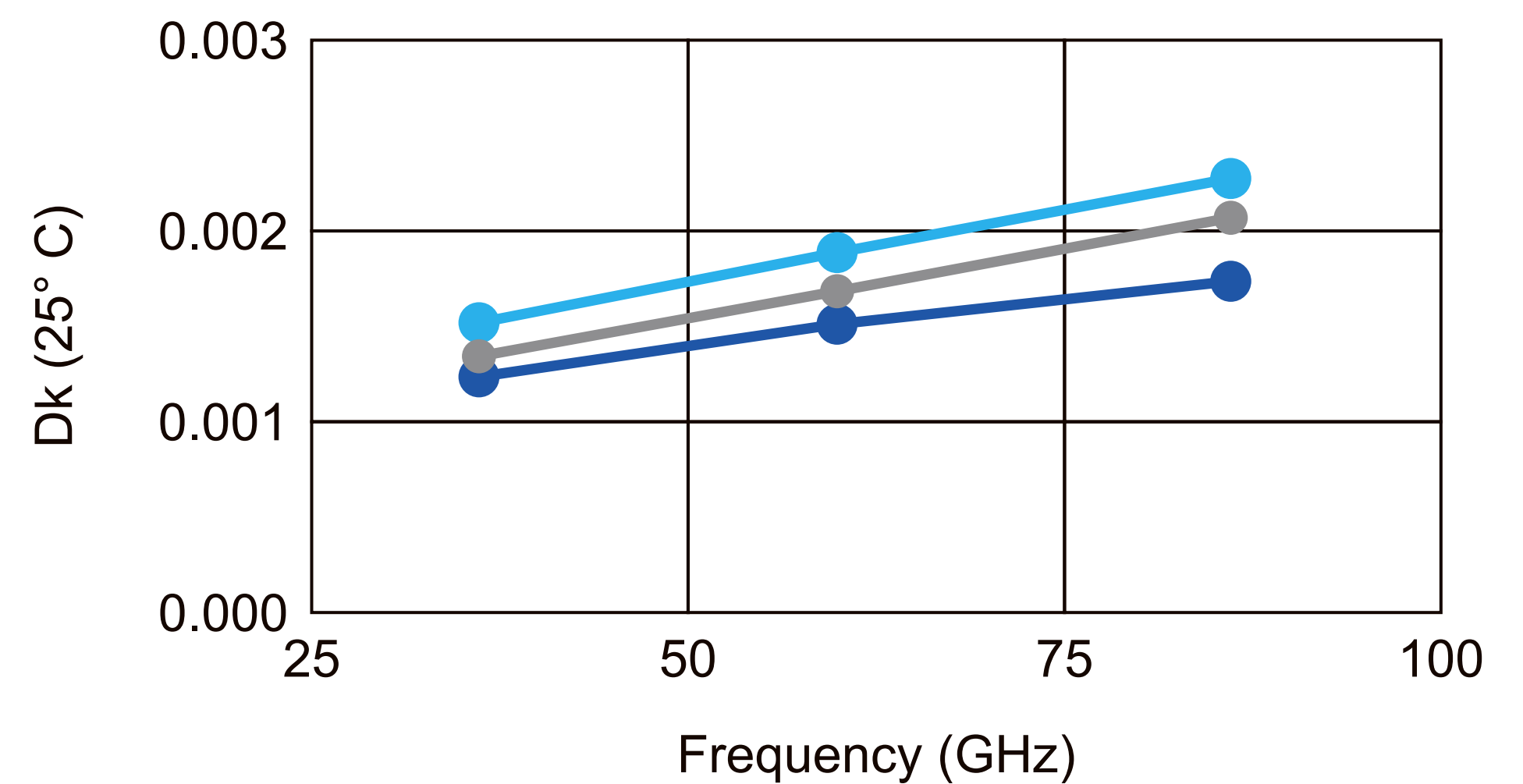
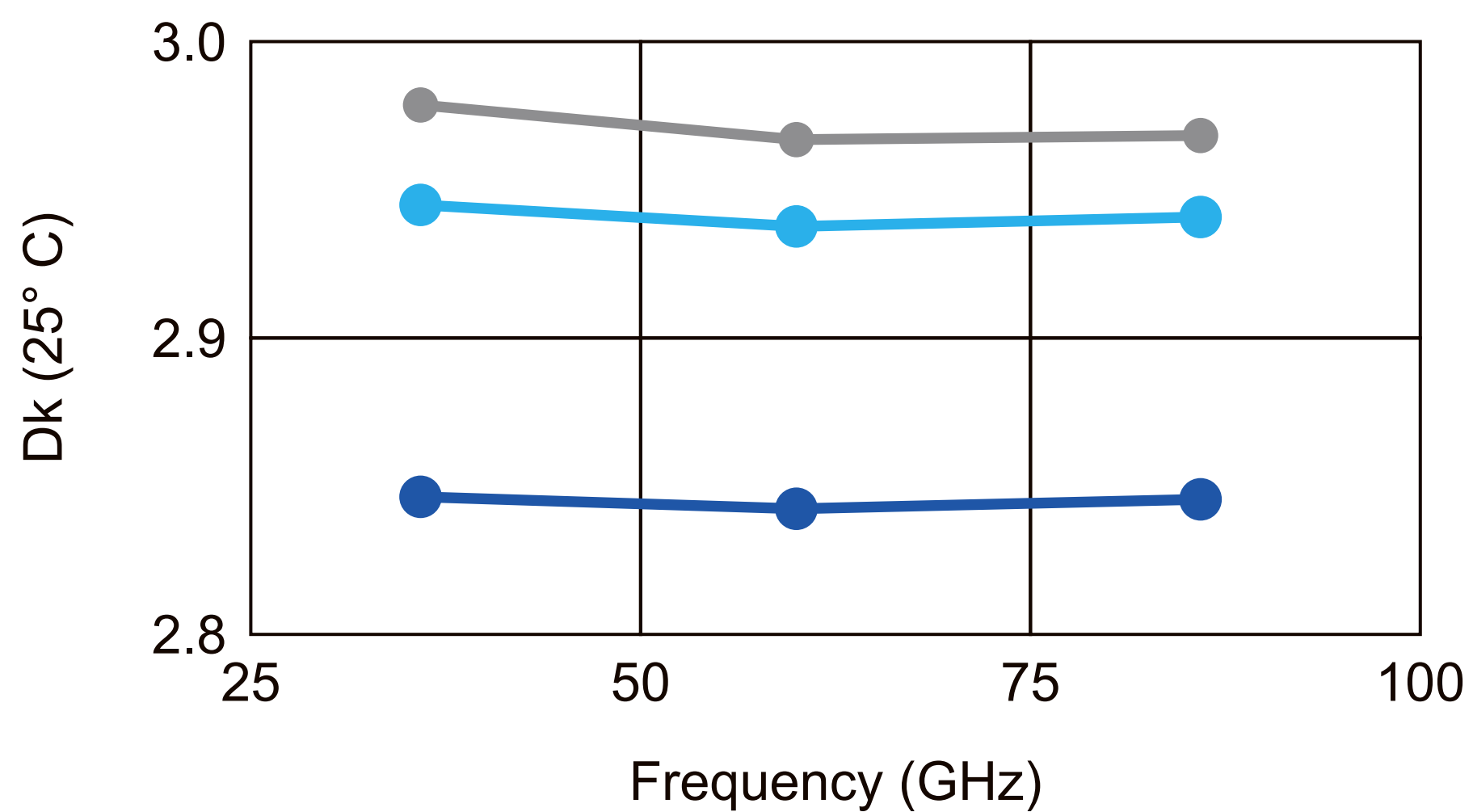
	CG-7001 CCL	CG-7003 CCL
Dk (10 GHz)	2.9	2.9
Df (10 GHz)	0.0011	0.0013
Tg (DMA)	217 °C	187 °C
Peel strength*	0.6 N/mm	0.7 N/mm
Solder test @300 °C	>300 sec	>300 sec



Composition: CG-7001/Silica/LDM-03(Denka)/SEBS/Flame retardants/Organic peroxide
CG-7003/CG-7001/Silica/SEBS/Flame retardants/Organic peroxide
*H-VLP3 Copper foil: Rz=0.5 μ m

- Frequency dependence of Dk/Df

●CG-7001 CCL ●CG-7003 CCL ●Commercially available CCL



- Temperature dependence of Dk/Df

●CG-7001 CCL ●CG-7003 CCL ●Commercially available CCL

